Title (en)

TRANSFER CHUCK FOR TRANSFERRING FLAT MATERIALS, PARTICULARLY WAFERS

Title (de)

TRANSFERCHUCK ZUR ÜBERTRAGUNG VON FLÄCHIGEN MATERIALIEN, INSBESONDERE WAFERN

Title (fr)

VENTOUSE DE TRANSFERT POUR TRANSFÉRER DES MATÉRIAUX PLATS, NOTAMMENT DES TRANCHES DE SILICIUM

Publication

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Application

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Priority

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Abstract (en)

[origin: WO2009027142A1] The present invention relates to a device for depositing a flat material, particularly a wafer (5), on a first holding device (3), particularly a chuck, and/or for removing the wafer (5) from the first holding device (3), wherein the wafer is transported by a second holing device (13) to and/or from the first holding device (3). The holding device is, for example, associated with a testing device (1), or generally a machining device for the flat material. The transfer time of the flat material from a robot (11) to the holding device (3) and back is to be shortened. The flat material is to be positioned exactly on the first holding device (3). Compared to the state of the art, conventional lifting pins (9) are to be omitted in the first holding device (3). Instead, the second holding device (13) or a transfer chuck is provided between the first holding device (3) and a third holding device or robot carrying device (7) such that the flat material can be sucked up via a vacuum and then dropped. In this way, the flat material is transported from and to the first holding device (3) or from and to the robot carrying device (7). Thus effective transfer of the flat material by a robot (11) to and/or from a first holding device (3) is provided. The present invention is preferably suitable for automatically testing wafers (5) having electronic or electro-optical components that are to be tested.

IPC 8 full level

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